Abstract

LEAD FRAME, SEMICONDUCTOR PACKAGE HAVING THE SAME, AND SEMICONDUCTOR PACKAGE MANUFACTURING METHOD

A lead frame for a semiconductor package includes a pad, a support portion where a plurality of leads are formed, and a tie bar for supporting the pad, in which one end of the tie bar is connected to the support portion and the other end thereof is connected to the pad, wherein the height from the support portion to the pad when the tie bar is down-set processed is greater than the height from the support portion to the pad when an encapsulation is formed.

Figure 8.